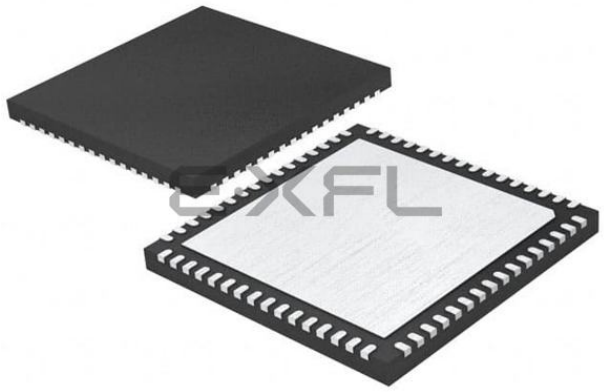
Microchip Technology - PIC32MX340F128H-80V/MR Datasheet



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Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx340f128h-80v-mr

Pin Diagrams (Continued)

121-Pin XBGA(1)

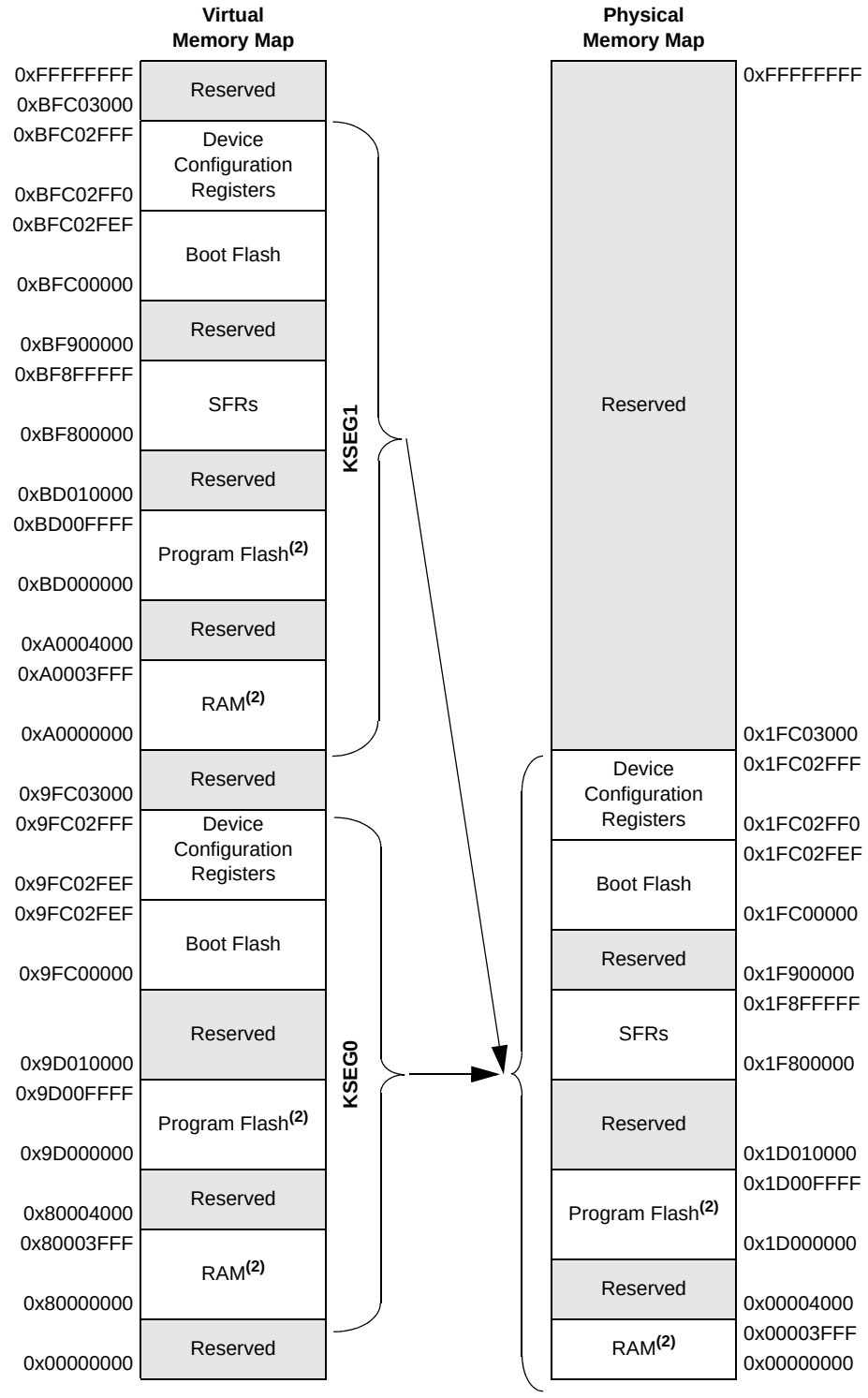
● = Pins are up to 5V tolerant

PIC32MX440F128L
PIC32MX460F256L
PIC32MX460F512L

	1	2	3	4	5	6	7	8	9	10	11
A	RE4	RE3	RG13	RE0	RG0	RF1	ENVREG	VSS	RD12	RD2	RD1
B	NC	RG15	RE2	RE1	RA7	RF0	VCORE/ VCAP	RD5	RD3	VSS	RC14
C	RE6	VDD	RG12	RG14	RA6	NC	RD7	RD4	VDD	RC13	RD11
D	RC1	RE7	RE5	VSS	VSS	NC	RD6	RD13	RD0	NC	RD10
E	RC4	RC3	RG6	RC2	VDD	RG1	VSS	RA15	RD8	RD9	RA14
F	$\overline{\text{MCLR}}$	RG8	RG9	RG7	VSS	NC	NC	VDD	RC12	VSS	RC15
G	RE8	RE9	RA0	NC	VDD	VSS	VSS	NC	RA5	RA3	RA4
H	RB5	RB4	VSS	VDD	NC	VDD	NC	VBUS	VUSB	RG2	RA2
J	RB3	RB2	RB7	AVDD	RB11	RA1	RB12	NC	NC	RF8	RG3
K	RB1	RB0	RA10	RB8	NC	RF12	RB14	VDD	RD15	RF3	RF2
L	RB6	RA9	AVSS	RB9	RB10	RF13	RB13	RB15	RD14	RF4	RF5

Note 1: Refer to Table 4 for full pin names.

FIGURE 4-2: MEMORY MAP ON RESET FOR PIC32MX320F064H DEVICE(1)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS61115)) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

TABLE 4-5: INTERRUPT REGISTERS MAP FOR PIC32MX440F128H, PIC32MX440F256H AND PIC32MX440F512H DEVICES ONLY(1)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT(2)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>						0000
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	—	—	—	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	—	—	—	—	—	—	USBIF	FCEIF	—	—	—	—	DMA3IF	DMA2IF	DMA1IF	DMA0IF	0000
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	0000
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	—	—	—	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	—	—	—	—	—	—	USBIE	FCEIE	—	—	—	—	DMA3IE	DMA2IE	DMA1IE	DMA0IE	0000
		15:0	RTCCIE	FSCMIE	I2C2MIE	I2C2SIE	I2C2BIE	U2TXIE	U2RXIE	U2EIE	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	0000
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>		—	—	—	CS1IP<2:0>			CS1IS<1:0>		0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>		—	—	—	CTIP<2:0>			CTIS<1:0>		0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>		—	—	—	OC1IP<2:0>			OC1IS<1:0>		0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>		—	—	—	T1IP<2:0>			T1IS<1:0>		0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>		—	—	—	OC2IP<2:0>			OC2IS<1:0>		0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>		—	—	—	T2IP<2:0>			T2IS<1:0>		0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>		—	—	—	OC3IP<2:0>			OC3IS<1:0>		0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>		—	—	—	T3IP<2:0>			T3IS<1:0>		0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>		—	—	—	OC4IP<2:0>			OC4IS<1:0>		0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>		—	—	—	T4IP<2:0>			T4IS<1:0>		0000
10E0	IPC5	31:16	—	—	—	—	—	—	—	—	—	—	—	OC5IP<2:0>			OC5IS<1:0>		0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>		—	—	—	T5IP<2:0>			T5IS<1:0>		0000
10F0	IPC6	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>		—	—	—	CNIP<2:0>			CNIS<1:0>		0000
		15:0	—	—	—	I2C1IP<2:0>			I2C1IS<1:0>		—	—	—	U1IP<2:0>			U1IS<1:0>		0000
1100	IPC7	31:16	—	—	—	SPI2IP<2:0>			SPI2IS<1:0>		—	—	—	CMP2IP<2:0>			CMP2IS<1:0>		0000
		15:0	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>		—	—	—	PMPIP<2:0>			PMPIS<1:0>		0000
1110	IPC8	31:16	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>		—	—	—	FSCMIP<2:0>			FSCMIS<1:0>		0000
		15:0	—	—	—	I2C2IP<2:0>			I2C2IS<1:0>		—	—	—	U2IP<2:0>			U2IS<1:0>		0000
1120	IPC9	31:16	—	—	—	DMA3IP<2:0>			DMA3IS<1:0>		—	—	—	DMA2IP<2:0>			DMA2IS<1:0>		0000
		15:0	—	—	—	DMA1IP<2:0>			DMA1IS<1:0>		—	—	—	DMA0IP<2:0>			DMA0IS<1:0>		0000
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	USBIP<2:0>			USBIS<1:0>		—	—	—	FCEIP<2:0>			FCEIS<1:0>		0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET, and INV registers at their virtual addresses, plus offsets of 0x4, 0x8, and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: This register does not have associated CLR, SET, and INV registers.

TABLE 4-6: INTERRUPT REGISTERS MAP FOR THE PIC32MX420F032H DEVICE ONLY(1)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT(2)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>						0000
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	—	—	—	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	—	—	—	—	—	—	USBIF	FCEIF	—	—	—	—	—	—	—	—	0000
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	0000
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	—	—	—	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	—	—	—	—	—	—	USBIE	FCEIE	—	—	—	—	—	—	—	—	0000
		15:0	RTCCIE	FSCMIE	I2C2MIE	I2C2SIE	I2C2BIE	U2TXIE	U2RXIE	U2EIE	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	0000
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>		—	—	—	CS1IP<2:0>			CS1IS<1:0>		0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>		—	—	—	CTIP<2:0>			CTIS<1:0>		0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>		—	—	—	OC1IP<2:0>			OC1IS<1:0>		0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>		—	—	—	T1IP<2:0>			T1IS<1:0>		0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>		—	—	—	OC2IP<2:0>			OC2IS<1:0>		0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>		—	—	—	T2IP<2:0>			T2IS<1:0>		0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>		—	—	—	OC3IP<2:0>			OC3IS<1:0>		0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>		—	—	—	T3IP<2:0>			T3IS<1:0>		0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>		—	—	—	OC4IP<2:0>			OC4IS<1:0>		0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>		—	—	—	T4IP<2:0>			T4IS<1:0>		0000
10E0	IPC5	31:16	—	—	—	—	—	—	—	—	—	—	—	OC5IP<2:0>			OC5IS<1:0>		0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>		—	—	—	T5IP<2:0>			T5IS<1:0>		0000
10F0	IPC6	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>		—	—	—	CNIP<2:0>			CNIS<1:0>		0000
		15:0	—	—	—	I2C1IP<2:0>			I2C1IS<1:0>		—	—	—	U1IP<2:0>			U1IS<1:0>		0000
1100	IPC7	31:16	—	—	—	SPI2IP<2:0>			SPI2IS<1:0>		—	—	—	CMP2IP<2:0>			CMP2IS<1:0>		0000
		15:0	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>		—	—	—	PMPIP<2:0>			PMPIS<1:0>		0000
1110	IPC8	31:16	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>		—	—	—	FSCMIP<2:0>			FSCMIS<1:0>		0000
		15:0	—	—	—	I2C2IP<2:0>			I2C2IS<1:0>		—	—	—	U2IP<2:0>			U2IS<1:0>		0000
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	USBIP<2:0>			USBIS<1:0>		—	—	—	FCEIP<2:0>			FCEIS<1:0>		0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: This register does not have associated CLR, SET, and INV registers.

TABLE 4-16: DMA CHANNELS 0-3 REGISTERS MAP FOR PIC32MX340FXXXX/360FXXXX/440FXXXX/460XXXX DEVICES ONLY(1)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3060	DCH0CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	CHCHNS	CHEN	CHAED	CHCHN	CHAEN	—	CHEDET	CHPRI<1:0>		0000
3070	DCH0ECON	31:16	—	—	—	—	—	—	—	—	CHAIRQ<7:0>								00FF
		15:0	CHSIRQ<7:0>								CFORCE	CABORT	PATEN	SIRQEN	AIRQEN	—	—	—	FF00
3080	DCH0INT	31:16	—	—	—	—	—	—	—	—	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE	0000
		15:0	—	—	—	—	—	—	—	—	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF	0000
3090	DCH0SSA	31:16	CHSSA<31:0>																0000
		15:0																	0000
30A0	DCH0DSA	31:16	CHDSA<31:0>																0000
		15:0																	0000
30B0	DCH0SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHSSIZ<7:0>								0000
30C0	DCH0DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHDSIZ<7:0>								0000
30D0	DCH0SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHSTR<7:0>								0000
30E0	DCH0DPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHDPTR<7:0>								0000
30F0	DCH0CSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHCSIZ<7:0>								0000
3100	DCH0CPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHCPTR<7:0>								0000
3110	DCH0DAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHPDAT<7:0>								0000
3120	DCH1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	CHCHNS	CHEN	CHAED	CHCHN	CHAEN	—	CHEDET	CHPRI<1:0>		0000
3130	DCH1ECON	31:16	—	—	—	—	—	—	—	—	CHAIRQ<7:0>								00FF
		15:0	CHSIRQ<7:0>								CFORCE	CABORT	PATEN	SIRQEN	AIRQEN	—	—	—	FF00
3140	DCH1INT	31:16	—	—	—	—	—	—	—	—	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE	0000
		15:0	—	—	—	—	—	—	—	—	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF	0000
3150	DCH1SSA	31:16	CHSSA<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers except DCHxSPTR, DCHxDPTR and DCHxCPTR have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

NOTES:

6.0 RESETS

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 7. "Resets"** (DS61118) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

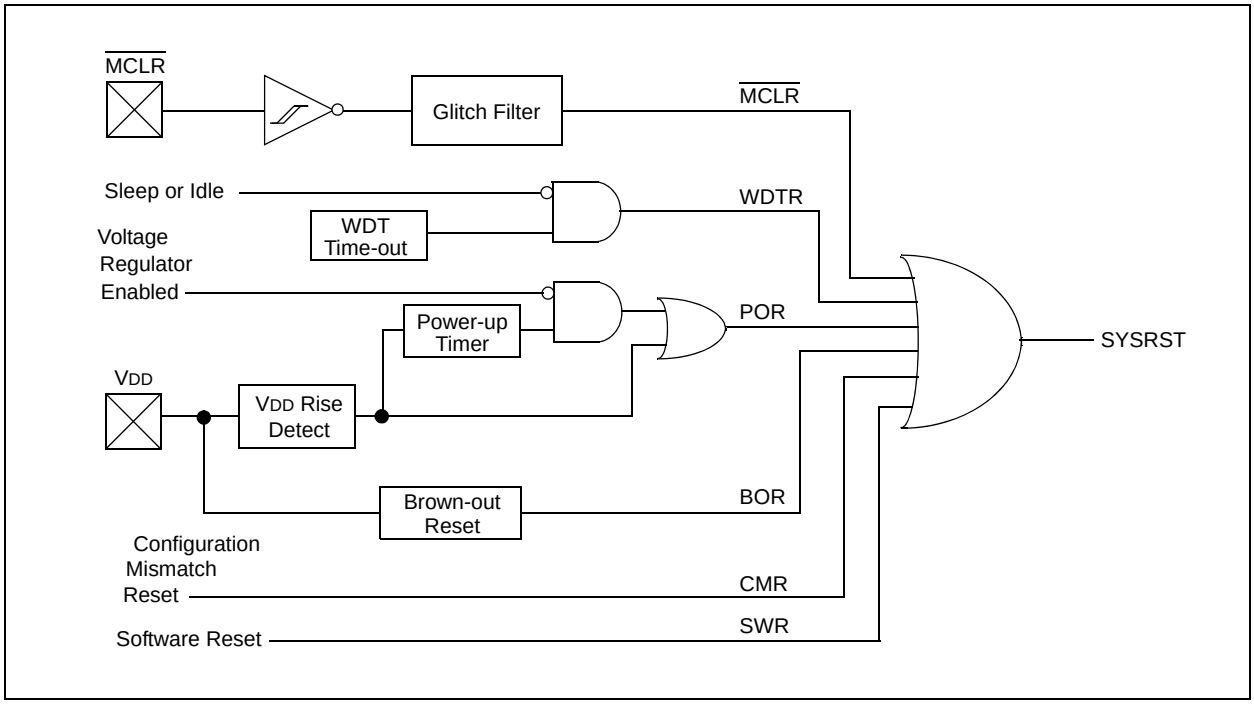
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Reset module combines all Reset sources and controls the device Master Reset signal, SYSRST. The following is a list of device Reset sources:

- POR: Power-on Reset
- $\overline{\text{MCLR}}$: Master Clear Reset Pin
- SWR: Software Reset
- WDTR: Watchdog Timer Reset
- BOR: Brown-out Reset
- CMR: Configuration Mismatch Reset

A simplified block diagram of the Reset module is illustrated in Figure 6-1.

FIGURE 6-1: SYSTEM RESET BLOCK DIAGRAM



NOTES:

18.0 INTER-INTEGRATED CIRCUIT™ (I^2C™)

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 24. "Inter-Integrated Circuit (I^2C™)"** (DS61116) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The I^2C module provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard. Figure 18-1 illustrates the I^2C module block diagram.

The PIC32MX3XX/4XX devices have up to two I^2C interface modules, denoted as I2C1 and I2C2. Each I^2C module has a 2-pin interface: the SCLx pin is clock and the SDAx pin is data.

Each I^2C module, 'I2Cx' (x = 1 or 2), offers the following key features:

- I^2C Interface Supporting both Master and Slave Operation.
- I^2C Slave Mode Supports 7 and 10-bit Address.
- I^2C Master Mode Supports 7 and 10-bit Address.
- I^2C Port allows Bidirectional Transfers between Master and Slaves.
- Serial Clock Synchronization for I^2C Port can be used as a Handshake Mechanism to Suspend and Resume Serial Transfer (SCLREL control).
- I^2C Supports Multi-master Operation; Detects Bus Collision and Arbitrates Accordingly.
- Provides Support for Address Bit Masking.

21.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 29. "Real-Time Clock and Calendar (RTCC)"** (DS61125) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

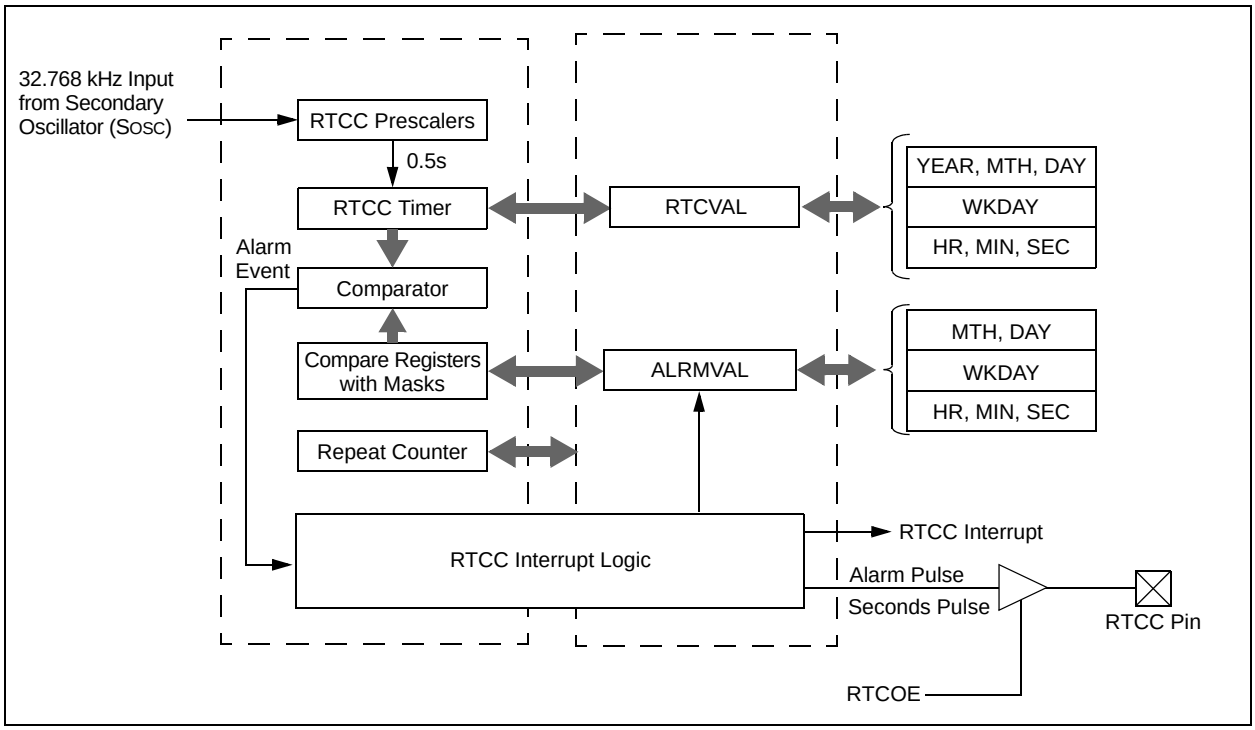
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The PIC32MX RTCC module is intended for applications in which accurate time must be maintained for extended periods of time with minimal or no CPU intervention. Low-power optimization provides extended battery lifetime while keeping track of time.

The following are some of the key features of this module:

- Time: Hours, Minutes and Seconds
- 24-Hour Format (Military Time)
- Visibility of One-Half-Second Period
- Provides Calendar: Weekday, Date, Month and Year
- Alarm Intervals are configurable for Half of a Second, One Second, 10 Seconds, One Minute, 10 Minutes, One Hour, One Day, One Week, One Month and One Year
- Alarm Repeat with Decrementing Counter
- Alarm with Indefinite Repeat: Chime
- Year Range: 2000 to 2099
- Leap Year Correction
- BCD Format for Smaller Firmware Overhead
- Optimized for Long-Term Battery Operation
- Fractional Second Synchronization
- User Calibration of the Clock Crystal Frequency with Auto-Adjust
- Calibration Range: ±0.66 Seconds Error per Month
- Calibrates up to 260 ppm of Crystal Error
- Requirements: External 32.768 kHz Clock Crystal
- Alarm Pulse or Seconds Clock Output on RTCC pin

FIGURE 21-1: RTCC BLOCK DIAGRAM



23.0 COMPARATOR

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. Refer to **Section 19. "Comparator"** (DS61110) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

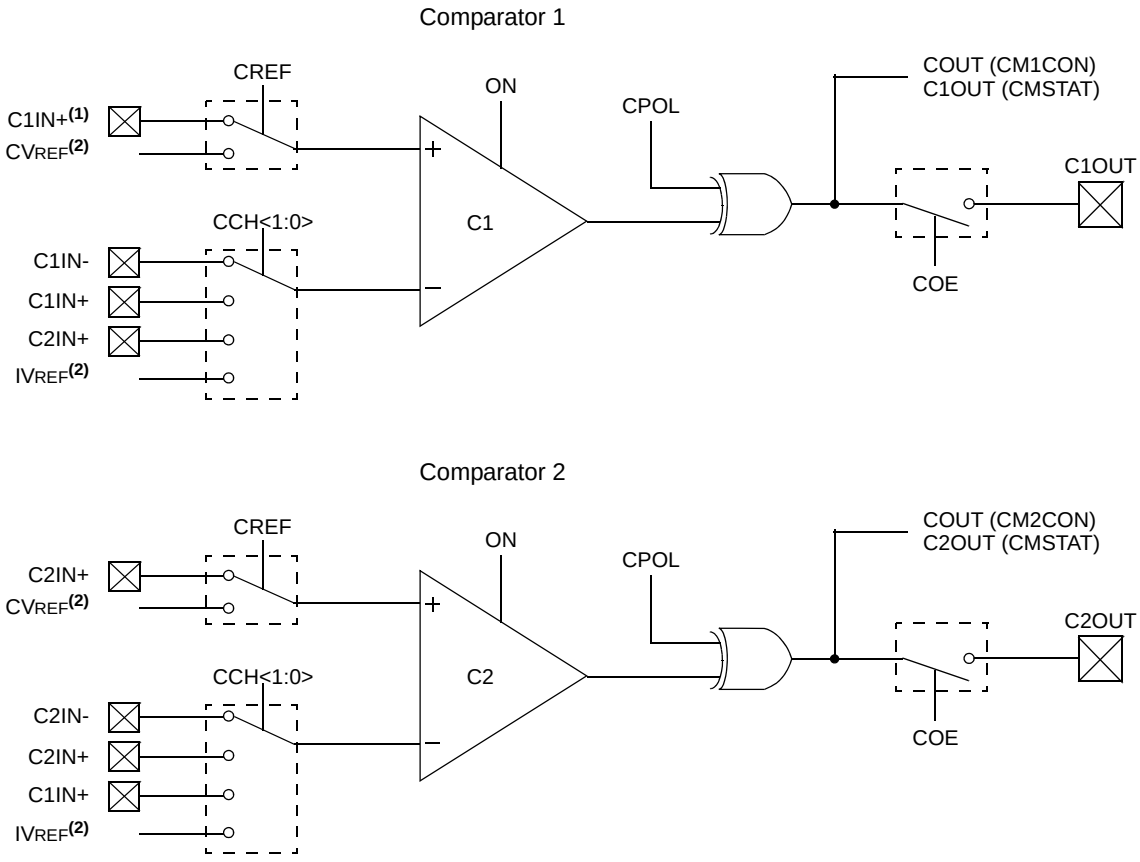
The PIC32MX3XX/4XX Analog Comparator module contains one or more comparator(s) that can be configured in a variety of ways.

Following are some of the key features of this module:

- Selectable inputs available include:
  - Analog inputs multiplexed with I/O pins
  - On-chip internal absolute voltage reference (IV_{REF})
  - Comparator voltage reference (CV_{REF})
- Outputs can be inverted
- Selectable interrupt generation

A block diagram of the comparator module is illustrated in Figure 23-1.

FIGURE 23-1: COMPARATOR BLOCK DIAGRAM



Note 1: On USB variants, when USB is enabled, this pin is controlled by the USB module and therefore is not available as a comparator input.

2: Internally connected.

REGISTER 26-2: DEVCFG1: DEVICE CONFIGURATION WORD 1

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	r-1	r-1
	—	—	—	—	—	—	—	—
23:16	R/P	r-1	r-1	R/P	R/P	R/P	R/P	R/P
	FWDTEN	—	—	WDTPS<4:0>				
15:8	R/P	R/P	R/P	R/P	r-1	R/P	R/P	R/P
	FCKSM<1:0>		FPBDIV<1:0>		—	OSCIOFNC	POSCMOD<1:0>	
7:0	R/P	r-1	R/P	r-1	r-1	R/P	R/P	R/P
	IESO	—	FSOSCEN	—	—	FNOSC<2:0>		

Legend:			
R = Readable bit	W = Writable bit	P = Programmable bit	r = Reserved bit
U = Unimplemented bit	-n = Bit Value at POR: (‘0’, ‘1’, x = Unknown)		

bit 31-24 **Reserved:** Write ‘1’

bit 23 **FWDTEN:** Watchdog Timer Enable bit
1 = The WDT is enabled and cannot be disabled by software
0 = The WDT is not enabled; it can be enabled in software

bit 22-21 **Reserved:** Write ‘1’

bit 20-16 **WDTPS<4:0>:** Watchdog Timer Postscale Select bits
10100 = 1:1048576
10011 = 1:524288
10010 = 1:262144
10001 = 1:131072
10000 = 1:65536
01111 = 1:32768
01110 = 1:16384
01101 = 1:8192
01100 = 1:4096
01011 = 1:2048
01010 = 1:1024
01001 = 1:512
01000 = 1:256
00111 = 1:128
00110 = 1:64
00101 = 1:32
00100 = 1:16
00011 = 1:8
00010 = 1:4
00001 = 1:2
00000 = 1:1
All other combinations not shown result in operation = ‘10100’

bit 15-14 **FCKSM<1:0>:** Clock Switching and Monitor Selection Configuration bits
1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled
01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled
00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled

Note 1: Do not disable POSC (POSCMOD = 00) when using this oscillator source.

29.1 DC Characteristics

TABLE 29-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)	Temp. Range (in °C)	Max. Frequency
			PIC32MX3XX/4XX
DC5	2.3V-3.6V	-40°C to +85°C	80 MHz **(Note 1)**
DC5b	2.3V-3.6V	-40°C to +105°C	80 MHz **(Note 1)**

Note 1: 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.

TABLE 29-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typical	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
V-Temp Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+105	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – S IOH) I/O Pin Power Dissipation: I/O = S ({VDD – VOH} x IOH) + S (VOL x IOL))	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 29-3: THERMAL PACKAGING CHARACTERISTICS

Characteristics	Symbol	Typical	Max.	Unit	Notes
Package Thermal Resistance, 121-Pin XBGA (10x10x1.1 mm)	θJA	40	—	°C/W	**1**
Package Thermal Resistance, 100-Pin TQFP (12x12x1 mm)	θJA	43	—	°C/W	**1**
Package Thermal Resistance, 64-Pin TQFP (10x10x1 mm)	θJA	47	—	°C/W	**1**
Package Thermal Resistance, 64-Pin QFN (9x9x0.9 mm)	θJA	28	—	°C/W	**1**

Note 1: Junction to ambient thermal resistance, Theta-JA (θJA) numbers are achieved by package simulations.

TABLE 29-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
Operating Voltage							
DC10	VDD	**Supply Voltage**	2.3	—	3.6	V	—
DC12	VDR	**RAM Data Retention Voltage (Note 1)**	1.75	—	—	V	—
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	1.75	—	1.95	V	—
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	—

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

TABLE 29-11: DC CHARACTERISTICS: PROGRAM MEMORY(3)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	1000	—	—	E/W	—
D131	VPR	VDD for Read	VMIN	—	3.6	V	—
D132	VPEW	VDD for Erase or Write	3.0	—	3.6	V	—
D134	TRETD	Characteristic Retention	20	—	—	Year	—
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
	TWW	Word Write Cycle Time	20	—	40	µs	—
D136	TRW	Row Write Cycle Time(2) (128 words per row)	3	4.5	—	ms	—
D137	TPE	Page Erase Cycle Time	20	—	—	ms	—
	TCE	Chip Erase Cycle Time	80	—	—	ms	—
D138	LVDstartup	Flash LVD Delay	—	—	6	µs	—

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

2: The minimum SYSCLK for row programming is 4 MHz. Care should be taken to minimize bus activities during row programming, such as suspending any memory-to-memory DMA operations. If heavy bus loads are expected, selecting Bus Matrix Arbitration mode 2 (rotating priority) may be necessary. The default Arbitration mode is mode 1 (CPU has lowest priority).

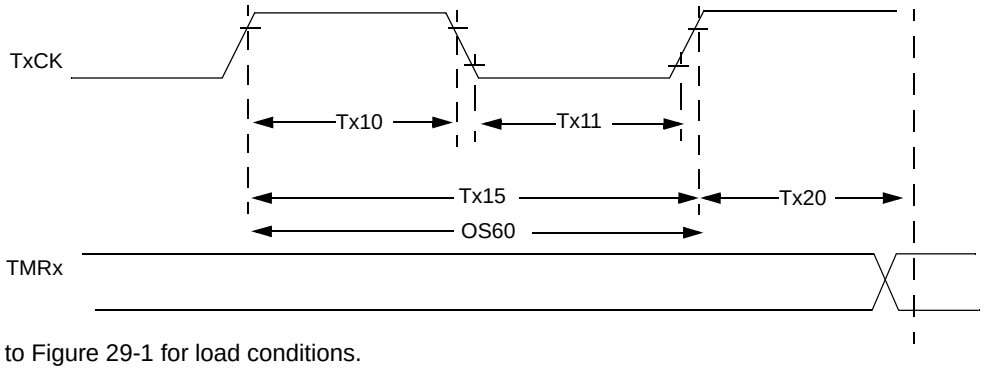
3: Refer to the "*PIC32MX Flash Programming Specification*" (DS61145) for operating conditions during programming and erase cycles.

TABLE 29-12: PROGRAM FLASH MEMORY WAIT STATE CHARACTERISTICS

DC CHARACTERISTICS	Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp		
Required Flash wait states	**SYSCLK**	**Units**	**Comments**
0 Wait State	0 to 30	MHz	—
1 Wait State	31 to 60		
2 Wait States	61 to 80		

Note 1: 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.

FIGURE 29-6: TIMER1, 2, 3, 4, 5 EXTERNAL CLOCK TIMING CHARACTERISTICS



Note: Refer to Figure 29-1 for load conditions.

TABLE 29-23: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS(1)

AC CHARACTERISTICS	Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp

Param. No.	Symbol	Characteristics(2)		Min.	Typical	Max.	Units	Conditions
TA10	TTXH	TxCK High Time	Synchronous, with prescaler	[(12.5 ns or 1TPB)/N] + 25 ns	—	—	ns	Must also meet parameter TA15.
			Asynchronous, with prescaler	10	—	—	ns	—
TA11	TTXL	TxCK Low Time	Synchronous, with prescaler	[(12.5 ns or 1TPB)/N] + 25 ns	—	—	ns	Must also meet parameter TA15.
			Asynchronous, with prescaler	10	—	—	ns	—
TA15	TTXP	TxCK Input Period	Synchronous, with prescaler	[(Greater of 25 ns or 2TPB)/N] + 30 ns	—	—	ns	VDD > 2.7V
				[(Greater of 25 ns or 2TPB)/N] + 50 ns	—	—	ns	VDD < 2.7V
			Asynchronous, with prescaler	20	—	—	ns	VDD > 2.7V **(Note 3)**
				50	—	—	ns	VDD < 2.7V **(Note 3)**
OS60	FT1	SOSC1/T1CK Oscillator Input Frequency Range (oscillator enabled by setting TCS bit (T1CON<1>))		32	—	100	kHz	—
TA20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		—		1	TPB	—

Note 1: Timer1 is a Type A.

2: This parameter is characterized, but not tested in manufacturing.

3: N = prescale value (1, 8, 64, 256)

TABLE 29-32: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

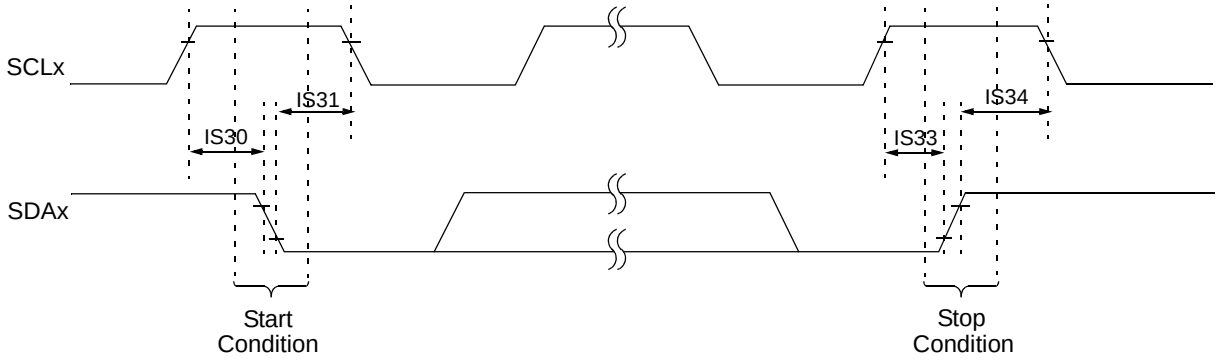
AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp			
Param. No.	**Symbol**	**Characteristics**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode(2)	TPB * (BRG + 2)	—	µs	
IM11	THI:SCL	Clock High Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode(2)	TPB * (BRG + 2)	—	µs	
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF.
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF.
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	100	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode(2)	0	0.3	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	Only relevant for Repeated Start condition.
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode(2)	TPB * (BRG + 2)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TPB * (BRG + 2)	—	µs	After this period, the first clock pulse is generated.
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode(2)	TPB * (BRG + 2)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode(2)	TPB * (BRG + 2)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TPB * (BRG + 2)	—	ns	—
			400 kHz mode	TPB * (BRG + 2)	—	ns	
			1 MHz mode(2)	TPB * (BRG + 2)	—	ns	
IM40	TAA:SCL	Output Valid from Clock	100 kHz mode	—	3500	ns	—
			400 kHz mode	—	1000	ns	
			1 MHz mode(2)	—	350	ns	
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	The amount of time the bus must be free before a new transmission can start.
			400 kHz mode	1.3	—	µs	
			1 MHz mode(2)	0.5	—	µs	
IM50	CB	Bus Capacitive Loading		—	400	pF	—
IM51	TPGD	Pulse Gobbler Delay(3)		52	312	ns	—

Note 1: BRG is the value of the I^2C™ Baud Rate Generator.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

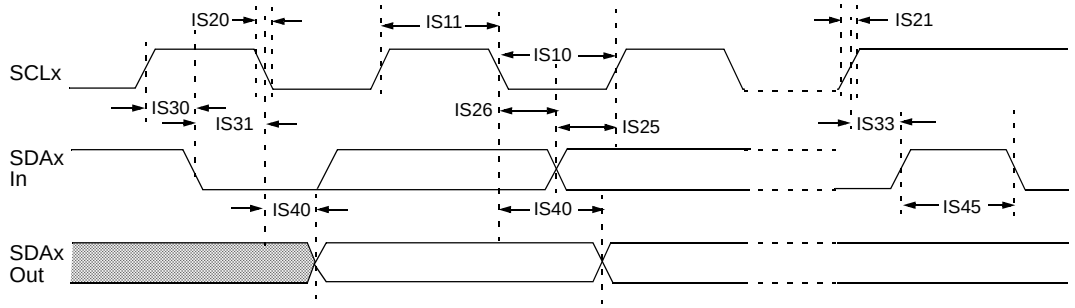
3: The typical value for this parameter is 104 ns.

FIGURE 29-16: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (SLAVE MODE)



Note: Refer to Figure 29-1 for load conditions.

FIGURE 29-17: I2Cx BUS DATA TIMING CHARACTERISTICS (SLAVE MODE)



Note: Refer to Figure 29-1 for load conditions.

FIGURE 29-22: PARALLEL MASTER PORT WRITE TIMING DIAGRAM

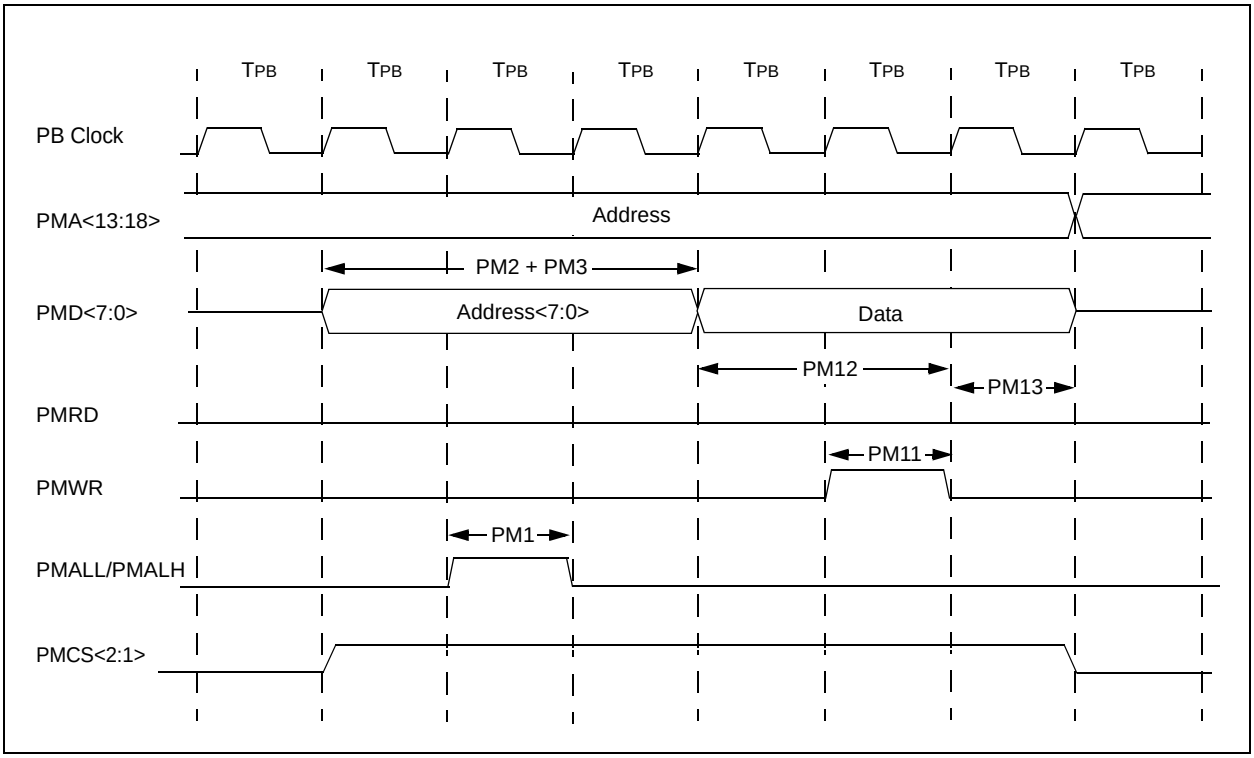


TABLE 29-39: PARALLEL MASTER PORT WRITE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
PM11	TWR	PMWR Pulse Width	—	1 TPB	—	—	—
PM12	TDVSU	Data Out Valid before PMWR or PMENB goes Inactive (data setup time)	—	2 TPB	—	—	—
PM13	TDVHOLD	PMWR or PMEMB Invalid to Data Out Invalid (data hold time)	—	1 TPB	—	—	—

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 29-23: EJTAG TIMING CHARACTERISTICS

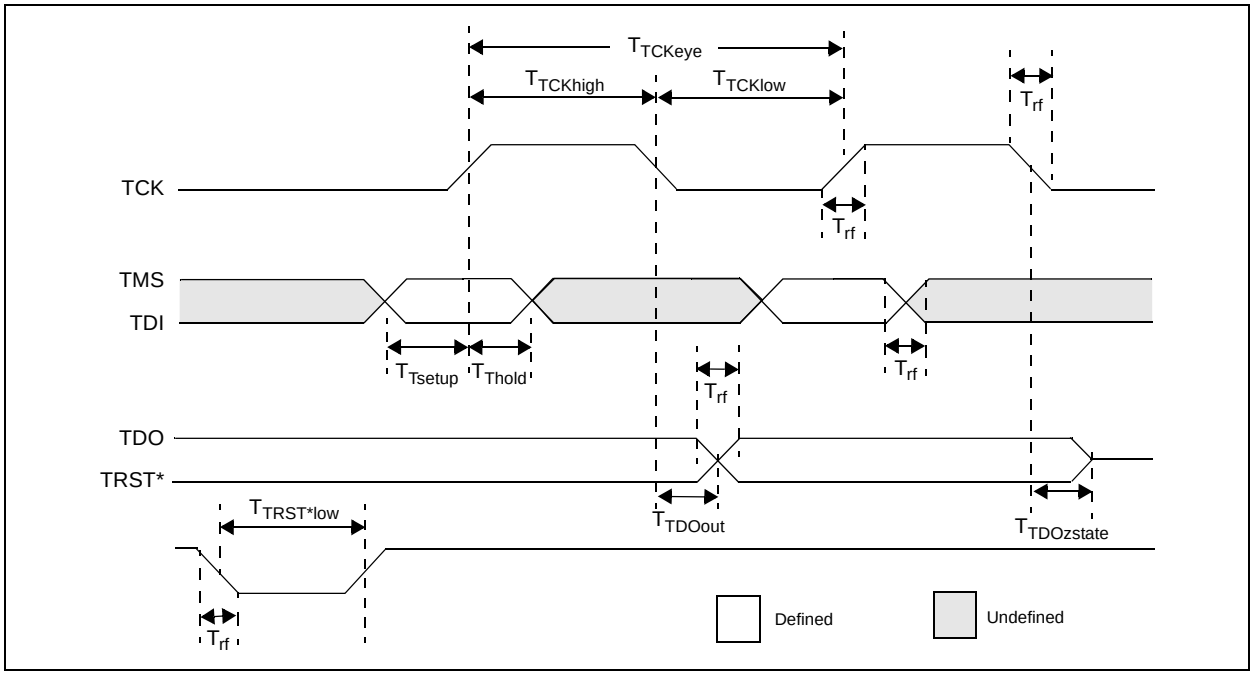


TABLE 29-41: EJTAG TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp			
Param. No.	**Symbol**	**Description(1)**	**Min.**	**Max.**	**Units**	**Conditions**
EJ1	TTCKCYC	TCK Cycle Time	25	—	ns	—
EJ2	TTCKHIGH	TCK High Time	10	—	ns	—
EJ3	TTCKLOW	TCK Low Time	10	—	ns	—
EJ4	TTSETUP	TAP Signals Setup Time Before Rising TCK	5	—	ns	—
EJ5	TTHOLD	TAP Signals Hold Time After Rising TCK	3	—	ns	—
EJ6	TTDOOUT	TDO Output Delay Time from Falling TCK	—	5	ns	—
EJ7	TTDOZSTATE	TDO 3-State Delay Time from Falling TCK	—	5	ns	—
EJ8	TTRSTLOW	TRST Low Time	25	—	ns	—
EJ9	TRF	TAP Signals Rise/Fall Time, All Input and Output	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

Revision H (May 2011)

The revision includes the following global update:

- All references to VDDCORE/VCAP have been changed to: VCORE/VCAP
- Added references to the new V-Temp temperature range: -40ºC to +105ºC

This revision also includes minor typographical and formatting changes throughout the data sheet text. Major updates are referenced by their respective section in the following table.

TABLE A-3: MAJOR SECTION UPDATES

Section Name	Update Description
Section 1.0 “Device Overview”	Updated the VBUS description in **Table 1-1: “Pinout I/O Descriptions”**.
Section 4.0 “Memory Organization”	Added Note 2 and changed the RIPL<2:0> bits to SRIPL<2:0> in the Interrupt Register Map tables (see Table 4-2 through Table 4-6. Added Note 2 to the Timer1-5 Register Map (see Table 4-7). Updated the All Resets value for I2C1CON<15:0> and I2C2CON<15:0> in the I2C1 and I2C2 Register Map (see Table 4-10). Updated the All Resets value for SPI1STAT<15:0> and SPI2STAT<15:0> in the SPI1 and SPI2 Register Map (see Table 4-12). Updated the All Resets value for CM1CON<15:0> and CM2CON<15:0> in the Comparator Register Map (see Table 4-17). Renamed the RCDIV<2:0> bits to FRCDIV<2:0> and the LOCK bit to SLOCK in the OSCCON register, and added Note 3 and the SYSKEYregister to the System Control Registers Map (see Table 4-20). Updated the All Resets value for the PMSTAT register in the Parallel Master Port Register Map (see Table 4-37). Updated the All Resets value for CHECON<15:0> and CHETAG<15:0> in the Prefetch Register Map (see Table 4-39). Renamed FUPLLEN, FUPLLIDIV, and FPLLMULT in the DEVCFG2 register to: UPLLEN, UPLLIDIV, and FPLLMUL, respectively in the Device Configuration Word Summary (see Table 4-41). Added Notes 1 through 4 to the USB Register Map (see Table 4-43).
Section 5.0 “Flash Program Memory”	Added a note on Flash LVD Delay and Example 5-1.
Section 8.0 “Oscillator Configuration”	Updated the PIC32MX3XX/4XX Family Clock Diagram (see Figure 8-1).
Section 11.0 “USB On-The-Go (OTG)”	Updated the PIC32MX3XX/4XX Family USB Interface Diagram (see Figure 11-1).
Section 16.0 “Output Compare”	Updated the Output Compare Module Block Diagram (see Figure 16-1).
Section 22.0 “10-bit Analog-to-Digital Converter (ADC)”	Updated the ADC Conversion Clock Period Block Diagram (see Figure 22-2).
Section 26.0 “Special Features”	Renamed FUPLLEN, FUPLLIDIV, and FPLLMULT in the DEVCFG2 register to: UPLLEN, UPLLIDIV, and FPLLMUL, respectively (see Register 26-3).